

IN THE SPECIFICATION:

Page 1, lines 1 to 4, replace the paragraph with the following amended paragraph.

BACKGROUND OF THE INVENTION

FIELD OF THE INVENTION

The present invention relates to printed circuit board (PCB) assemblies and particularly, but not exclusively, to a system for shielding components from radio frequency interference (RFI), and more particularly to a system for shielding surface mounted devices (SMD).

THE PRIOR ART

Page 1, lines 18 to 21, delete the paragraph and replace with the following topic heading.

~~A first aspect of the present invention provides a printed circuit board (PCB) assembly as recited in the appended independent claim 1. An assembly comprising further novel and advantages features is provided as recited in any of the appended dependent claims 1 to 9.~~

SUMMARY OF THE INVENTION

Page 2, lines 30 and 31, replace the paragraph with the following amended paragraph.

Embodiments of the present invention will now be described with reference to the accompanying drawings, ~~in which:~~

Page 3, before line 1, insert the following topic heading.

BRIEF DESCRIPTION OF THE DRAWINGS

Page 3, between lines 23 and 24, insert the following topic heading.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS